

ISSP 2026

30 June - 3 July 2026
Kyoto Research Park
Kyoto, Japan

THE 18th INTERNATIONAL SYMPOSIUM ON SPUTTERING & PLASMA PROCESSES

<http://www.issp-jvss.org>

TOPICAL THEME:

**Advancements in Sputtering & Plasma Processes
for a Connected Future**

ISSP Special Tutorial, 30 June

Jochen Schneider (RWTH Aachen University, Germany)

ISSP Regular Scientific Sessions, 1-3 July

INVITED SPEAKERS:

G. Abadias (Université de Poitiers)
A. Anders (Plasma Engineering LLC)
R. Bandorf (Fraunhofer IST)
E. v. Hauff (Fraunhofer FEP)
M. Horprathum (NECTEC)
C. L. Hsiao (Linköping University)
N. P. Kobayashi (University of California Santa Cruz)
P. H. Mayrhofer (TU Wien)
M. Rudolph (Leibniz Institute of Surface Engineering (IOM))
J. T. Guðmundsson (University of Iceland)
K. Ueno (Yokohama National University)
F. B. Wu (National United University)

ORGANIZED by

The Japan Society of Vacuum and Surface Science



PERTNERSHIP by AVS



Advance Registration Fee for Regular Scientific Sessions (Including one Copy of On-site Proceedings):

Research Division -Sputtering and Plasma Members: ¥50,000 / Sponsoring Society Members: ¥55,000 /
Assisting Society Members: ¥57,000 / Students: ¥30,000 / Others: ¥65,000.

Advance registration deadline: 3 June 2026 (Fees will increase by ¥5,000 after 3 June 2026)

Registration Fee for Special Tutorial:

Regular (Attendee of Scientific Sessions): ¥10,000 / Regular (Only Tutorial): ¥40,000 / Students: ¥5,000

Registration deadline: 3 June, 2026 (Registration for tutorial cannot be acceptable after 3 June, 2026)

Further Information:

ISSP 2026 Secretariat, e-mail: secretariat@issp-jvss.org URL: <https://www.issp-jvss.org>

The Japan Society of Vacuum and Surface Science

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Abstract deadline: 26 December 2025

